### SAPPORO JAPAN MAY 26-29 2019

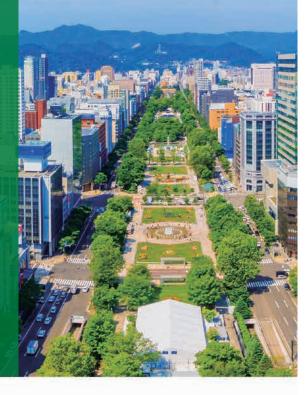
# ISCAS 2019

IEEE International Symposium on Circuits and Systems



## Call for Papers

The IEEE International Symposium on Circuits and Systems (ISCAS) is the world's premier networking forum for leading researchers in the highly active fields of theory, design and implementation of circuits and systems. ISCAS is the flagship conference of the IEEE Circuits and Systems Society. ISCAS 2019 will be held in Sapporo, Hokkaido, Japan from May 26 to 29, 2019. ISCAS 2019 will have a special focus on Circuits and Systems for Sustainable Society in Harmony with Nature, and seeks to address multidisciplinary challenges in circuits and systems. The symposium will include oral and poster sessions, live demonstrations, tutorials given by experts on state-of-the-art topics, and special sessions, with the aim of complementing the regular program with emerging topics of particular interest to the circuits and systems community.



#### To implement the above vision, this year's meeting will highlight the following innovation themes:

- Society 5.0 Human-centric Society
- Sustainable Computing and Systems
- Energy-aware Systems and Services
- Disaster Prevention and Mitigation
- Smart Systems for Automotive
- Cyber-Physical Systems
- · AI, IoT and Big Data Processing

#### by collecting contributions in all areas of Circuits and Systems, including but not limited to the following topics:

- Analog / Mixed Signal Circuits & Systems
- Beyond CMOS: Nano & Hybrid Systems
- Communications Circuits & Systems
- Neural Networks & Neuromorphic Engineering
- Power and Energy Circuits & Systems
- Visual Communications & Multimedia Signal Processing
- Biomedical Circuits & Systems
- Digital Circuits & Systems
- Digital Signal Processing
- Nonlinear Systems & Circuit Theory
- Sensory Circuits & Systems
- Education in Circuits & Systems

#### **ISCAS 2019 Organizing Committee**

- Honorary Chair
- Hiroto Yasuura, Kyushu Univ.
- General Chair
- Yoshikazu Miyanaga, Hokkaido Univ.
- General Co-Chairs
- Hitoshi Kiya, Tokyo Metropolitan Univ. Moncef Gabbouj, Tampere Univ. of Technology
- Technical Program Chair Takao Onoye, Osaka Univ.
- Technical Program Co-Chairs
- Yoshifumi Nishio, Tokushima Univ. Tokunbo Ogunfunmi, Santa Clara Univ. Gabriel Rincón-Mora, Georgia Institute of Technology
- Special Session Co-Chairs
- Eryk Dutkiewicz, Univ. of Technology Sydney Atsushi Takahashi, Tokyo Institute of Technology Hiroo Sekiya, Chiba Univ
- Andrei Vladimirescu, ISEP/UC Berkeley
- Tutorial Co-Chairs
- Kaoru Arakawa, Meiji Univ. Shigetaka Takagi, Tokyo Institute of Technology Sandro Carrara, EPFL
- Finance Co-Chairs Mitsunori Makino, Chuo Univ. Koichi Ichige, Yokohama National Univ. Mounir Boukadoum, UQAM
- YPP Special Session Chair Elena Blokhina, Univ. College Dublin
- Plenary Session Co-Chairs Tohru Ishihara, Kyoto Univ.
- Franco Maloberti, Univ. of Pavia Publicity Co-Chairs
- Hiroshi Tamura, Chuo Univ. Nozomu Togawa, Waseda Univ. Kosin Chamnongthai, KMUTT Yann Deval, Univ. of Bordeaux
- Publication Co-Chairs
- Akira Taguchi, Tokyo City Univ. Yoko Uwate, Tokushima Univ.
- Industry & Exhibition Co-Chairs Akihiko Sugiyama, NEC Corporation Takayuki Nakachi, NTT Martins Rui, Univ. of Macau
- Demo Co-Chairs
- Mineo Kaneko, JAIST Yuichi Nakamura, NEC Corporation Edoardo Bonizzoni, Univ. of Pavia
- Local Arrangement Co-Chairs Tetsuya Asai, Hokkaido Univ.
- Tomoaki Sato, Hokusei Gakuen Univ. Registration Chair
- Hiroshi Ochi, Kyushu Institute of Technology
- Website Coordinator Kiyoshi Nishikawa, Tokyo Metropolitan Univ.
- WiCAS Co-Chairs
- Pau-Choo (Julia) Chung, National Cheng Kung Univ. Supavadee Aramvith, Chulalongkorn Univ. Maria Trocan, ISEP Jennifer Blain Christen, Arizona State Univ
- Management Co-Chairs
- Hiroshi Tsutsui, Hokkaido Univ. Ittetsu Taniguchi, Osaka Univ.
- Masayuki Kurosaki, Kyushu Institute of Technology
- International Advisory
- Shuji Tsukiyama, Chuo Univ.
- Akinori Nishihara, Tokyo Institute of Technology Thanos Stouraitis, Khalifa Univ.
- Maciej Ogorzałek, Jagiellonian Univ. Myung Hoon Sunwoo, Ajou Univ. Amara Amara. Tdh Foundation Gianluca Setti. Politecnico di Torino Kukjin Chun, Seoul National Univ.

invited for possible publication in the IEEE Trans. on Circuits and Systems -Part I, in the IEEE Trans. on Circuits and Systems – Part II, or in the IEEE Trans. on Biomedical Circuits and Systems.

Special Session proposals: 8 Oct. 2018 31 Oct. 2018 Papers submission: Live Demo proposals: 19 Nov. 2018 17 Dec. 2018 **Tutorials proposals:** Notification of acceptance: 24 Jan. 2019 Final Submission deadline: 18 Feb. 2019

IEEE International Symposium on Circuits & Systems,

Sapporo, Japan, May 26-29 2019





